

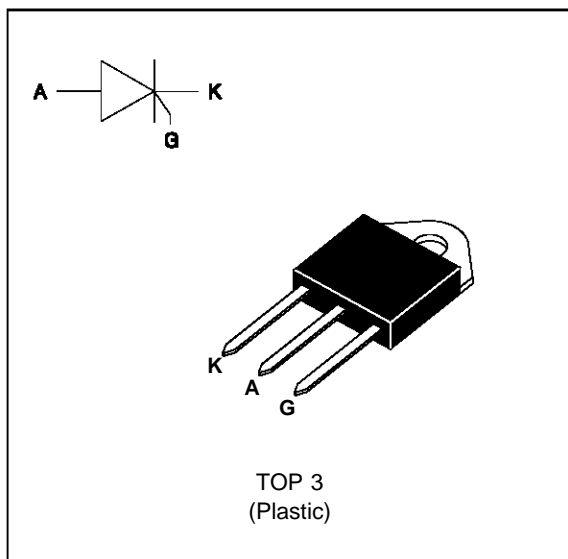
FEATURES

- HIGH SURGE CAPABILITY
- HIGH ON-STATE CURRENT
- HIGH STABILITY AND RELIABILITY
- BTW 69 Serie :
INSULATED VOLTAGE = 2500V_(RMS)
(UL RECOGNIZED : E81734)

DESCRIPTION

The BTW 69 (N) Family of Silicon Controlled Rectifiers uses a high performance glass passivated technology.

This general purpose Family of Silicon Controlled Rectifiers is designed for power supplies up to 400Hz on resistive or inductive load.



ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value	Unit	
I _{T(RMS)}	RMS on-state current (180° conduction angle)	BTW 69	T _c =70°C	50	A
		BTW 69 N	T _c =75°C	55	
I _{T(AV)}	Average on-state current (180° conduction angle, single phase circuit)	BTW 69	T _c =70°C	32	A
		BTW 69 N	T _c =75°C	35	
I _{TSM}	Non repetitive surge peak on-state current (T _j initial = 25°C)		tp=8.3 ms	525	A
			tp=10 ms	500	
I ² t	I ² t value		tp=10 ms	1250	A ² s
di/dt	Critical rate of rise of on-state current Gate supply : I _G = 100 mA di _G /dt = 1 A/μs			100	A/μs
T _{stg} T _j	Storage and operating junction temperature range			- 40 to + 150 - 40 to + 125	°C °C
T _l	Maximum lead temperature for soldering during 10 s at 4.5 mm from case			230	°C

Symbol	Parameter	BTW 69		BTW 69 / BTW 69 N				Unit
		200	400	600	800	1000	1200	
V _{DRM} V _{RRM}	Repetitive peak off-state voltage T _j = 125 °C	200	400	600	800	1000	1200	V

THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
Rth (j-a)	Junction to ambient		50	°C/W
Rth (j-c) DC	Junction to case for DC		BTW 69	°C/W
			BTW 69 N	

GATE CHARACTERISTICS (maximum values)

$P_G (AV) = 1W$ $P_{GM} = 40W$ ($t_p = 20 \mu s$) $I_{FGM} = 8A$ ($t_p = 20 \mu s$) $V_{RGM} = 5 V$.

ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions			Value		Unit
				BTW 69	BTW 69 N	
I_{GT}	$V_D=12V$ (DC) $R_L=33\Omega$	$T_j=25^\circ C$	MAX	80		mA
V_{GT}	$V_D=12V$ (DC) $R_L=33\Omega$	$T_j=25^\circ C$	MAX	1.5		V
V_{GD}	$V_D=V_{DRM}$ $R_L=3.3k\Omega$	$T_j=125^\circ C$	MIN	0.2		V
tgt	$V_D=V_{DRM}$ $I_G = 200mA$ $di_G/dt = 1.5A/\mu s$	$T_j=25^\circ C$	TYP	2		μs
I_L	$I_G = 1.2 I_{GT}$	$T_j=25^\circ C$	TYP	50		mA
I_H	$I_T = 500mA$ gate open	$T_j=25^\circ C$	MAX	150		mA
V_{TM}	BTW 69 $I_{TM} = 100A$ BTW 69 N $I_{TM} = 110A$ $t_p = 380\mu s$	$T_j=25^\circ C$	MAX	1.9	2.0	V
I_{DRM} I_{RRM}	V_{DRM} Rated V_{RRM} Rated	$T_j=25^\circ C$	MAX	0.02		mA
		$T_j=125^\circ C$		6		
dV/dt	Linear slope up to $V_D=67\%V_{DRM}$ gate open	$V_{DRM} \leq 800V$ $V_{DRM} \geq 1000V$	$T_j=125^\circ C$	MIN	500 250	V/ μs
tq	$V_D=67\%V_{DRM}$ $I_{TM}=110A$ $V_R=75V$ $di_{TM}/dt=30 A/\mu s$ $dV_D/dt=20V/\mu s$	$T_j=125^\circ C$	TYP	100		μs

Package	$I_{T(RMS)}$	V_{DRM} / V_{RRM}	Sensitivity Specification
	A	V	BTW
BTW 69 (Insulated)	50	200	X
		400	X
		600	X
		800	X
		1000	X
		1200	X
BTW 69 N (Uninsulated)	55	600	X
		800	X
		1000	X
		1200	X

Fig.1 : Maximum average power dissipation versus average on-state current (BTW 69).

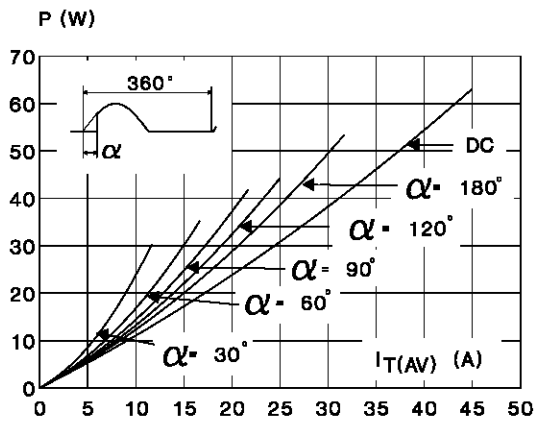


Fig.3 : Maximum average power dissipation versus average on-state current (BTW 69 N).

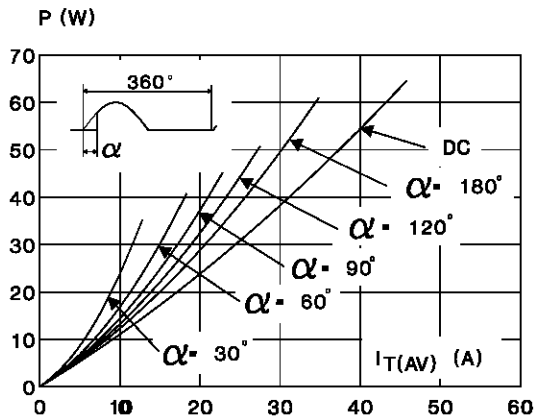


Fig.2 : Correlation between maximum average power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact (BTW 69).

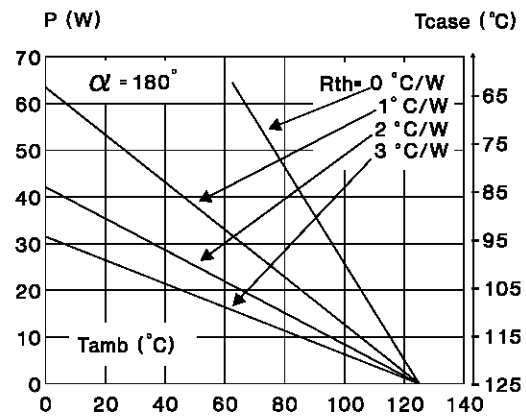


Fig.4 : Correlation between maximum average power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact (BTW 69 N).

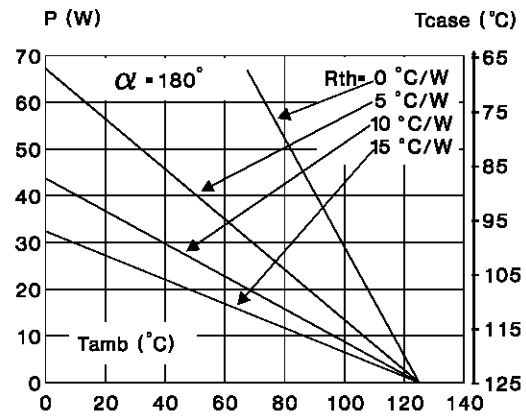


Fig.5 : Average on-state current versus case temperature (BTW 69).

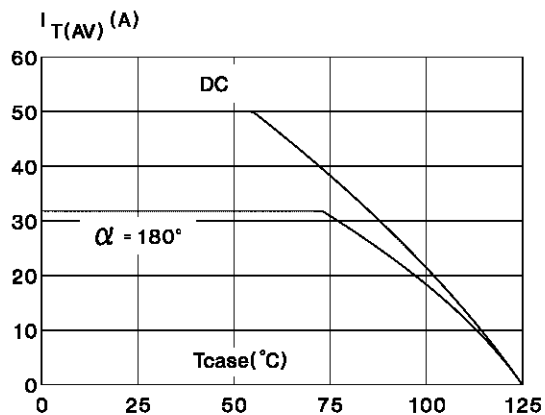


Fig.6 : Average on-state current versus case temperature (BTW 69 N).

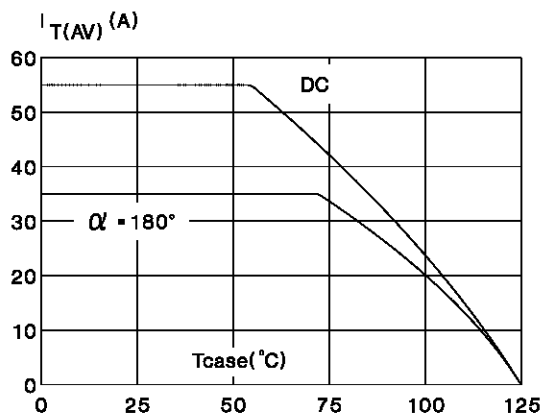


Fig.7 : Relative variation of thermal impedance versus pulse duration.

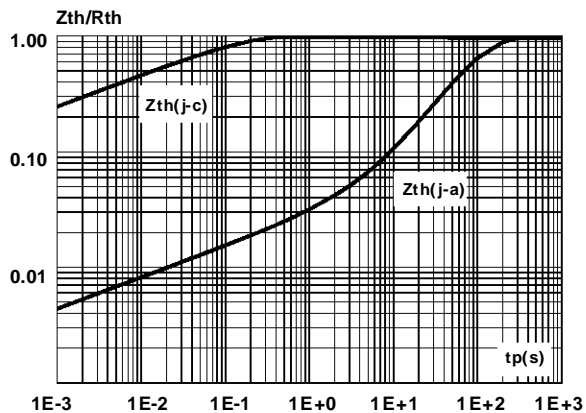


Fig.8 : Relative variation of gate trigger current versus junction temperature.

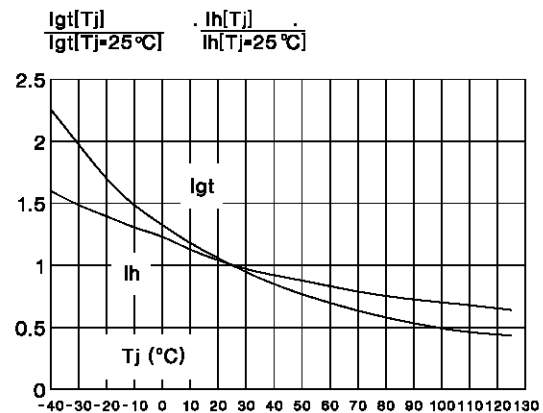


Fig.9 : Non repetitive surge peak on-state current versus number of cycles.

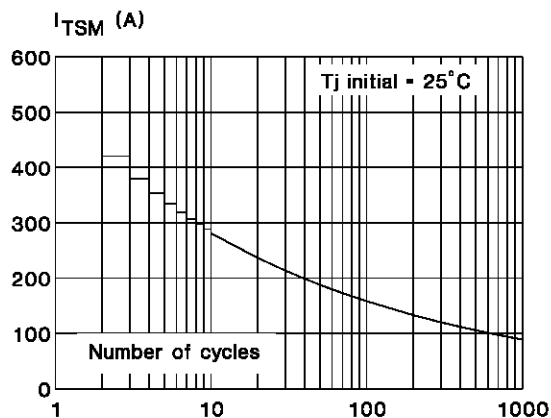


Fig.10 : Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t \leq 10$ ms, and corresponding value of I^2t .

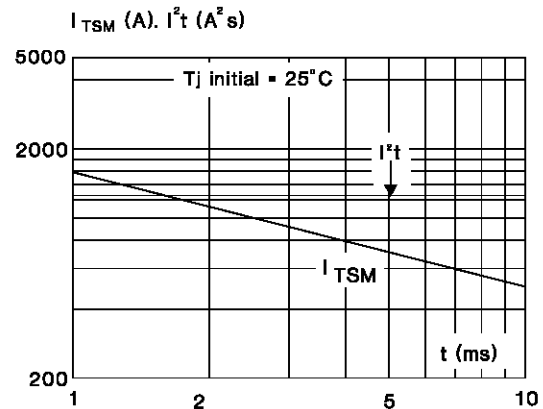
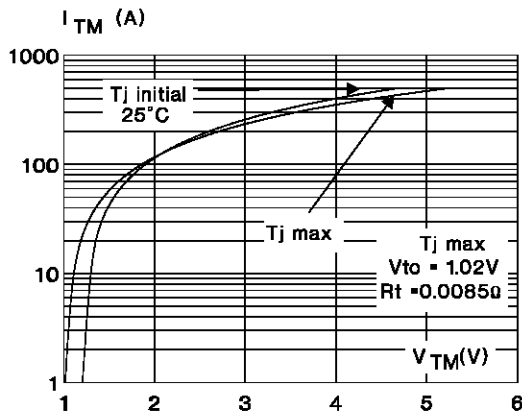
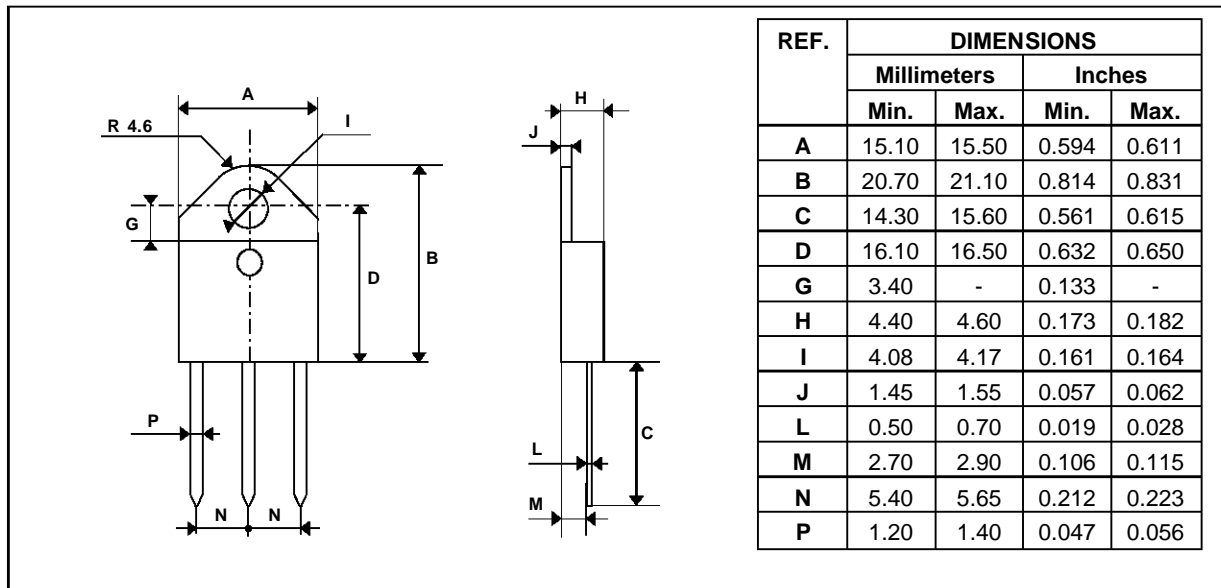


Fig11 : On-state characteristics (maximum values).



PACKAGE MECHANICAL DATA

TOP 3 Plastic



Cooling method : C
 Marking : type number
 Weight : 4.7 g

Recommended torque value : 0.8 m.N.
 Maximum torque value : 1 m.N.

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